Supplementary Materials

Large-scale fabrication, 3D tomography, and lithium-ion battery application of porous silicon

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• **Fe and Al concentration in ball-milled metallurgical Si**

Iron (Fe) and aluminum (Al) are the two major impurities. To determine their concentration in metallurgical silicon after ball milling, 0.5 g sample was put into polytetrafluoroethylene (PTFE) beaker containing 5 ml concentrated nitric acid (HNO₃). 5 ml hydrofluoric acid (HF, 50 wt. %) was then added by droplets to dissolve the
sample to get a clear solution. The solution was added with additional 5 ml acid mixture (sulfuric acid ($\text{H}_2\text{SO}_4$): phosphorous acid ($\text{H}_3\text{PO}_4$) = 3 : 2 by volume) and kept at 130 °C for 5 min. At this stage, all the silicon was converted to silicon tetrafluoride (SiF$_4$) and removed by volatilization, leaving only boron in the solution. The solution was then cooled down, and diluted with DI water. Fe and Al concentration measurements were performed using HORIBA Jobin Yvon ULTIMA-C inductively coupled plasma emission spectrometer (ICP-AES). After ball-milling, atomic percentage of Fe and Al in silicon powder are 1.9% and 0.47%, respectively. The feature size of the silicon powder after ball-milling is around 1 μm, as shown in Figure S1.

![Figure S1. SEM image of silicon powder after ball-milling.](image)

- **Pore size distribution of porous (Si(1))**
- ![Figure S2. Pore size distribution of porous Si(1)](image)
• **X-ray diffraction of porous Si(1)**

Coherent domain size can be calculated using Scherrer formula, which gives an average domain size of 19 nm. Figure S3 shows the XRD pattern of porous Si(1).

![XRD pattern of porous Si(1)](image)

**Figure S3.** XRD pattern of porous Si(1)

• **First principle calculation**

First-principle calculations were performed using the VASP code\(^1\). The ultrasoft pseudopotentials were used to model electron-ion interactions. Structure relaxation was carried out using the generalized gradient approximation (GGA) for exchange-correlation function\(^2\). The k-space integration was done by summing over the Monkhorst-Pack special points in the Brillouin zone. The Gaussian method, with a smearing width of 0.05 eV was used in determination of the Fermi level. The plane wave basis set was restricted by cutoff energy of 425 eV. Defect calculations were performed using 3x3x3 supercells corresponding to \(\sim 0.5\%\) defect concentration, and 2x2x2 k-point mesh was used for total energy calculations. The forces acting on the relaxed atoms are <0.02 eV/Å in the optimized structures.

• **Reactions between Fe(NO\(_3\))\(_3\) and Si:**

Both Fe\(^{3+}\) and NO\(_3^-\) can oxidize Si. The reaction between Fe\(^{3+}\) and Si is shown as:

\[ 4\text{Fe}^{3+} + \text{Si} + 6\text{F}^- \rightarrow 4\text{Fe}^{2+} + [\text{SiF}_6]^{3-} \]

However, NO\(_3^-\) has a complex behavior in the acidic environment (in the present of HF):
\[
\begin{align*}
\text{NO}_3^- + \text{H}^+ & \leftrightarrow \text{HNO}_3 \\
\text{H}^+ + \text{NO}_2^- + \text{HNO}_3 & \rightarrow 2\text{NO}_2 + \text{H}_2\text{O} \\
2\text{NO}_2 + \text{Si} & \rightarrow \text{Si}^{2+} + 2\text{NO}_2^- \\
\text{Si}^{2+} + 2(\text{OH})^- + 6\text{HF} & \rightarrow \text{H}_3\text{SiI}_n + \text{H}_2\text{O} + \text{H}_2
\end{align*}
\]

According to the Nernst equation: 
\[
E = E^0 + \frac{RT}{nF} \ln \frac{a_{\text{ox}}}{a_{\text{red}}},
\]
increase of \([\text{H}^+]\) concentration will increase the oxidation potential.

- **Morphology of Si(1), Si(3) and Si etched with additional HNO\textsubscript{3}**

Another control experiment was conducted to help to identify the role that NO\textsubscript{3}^- played in the etching process. In the experiment, similar to the etch condition as for Si(1), Fe(NO\textsubscript{3})\textsubscript{3} was reduced by 20% and replaced by HNO\textsubscript{3} to keep total concentration of NO\textsubscript{3}^- a constant. This sample is denoted as Si(3). Figure S4 compares the morphology of Si(1) and Si(3) using SEM and TEM. The structure of the two samples is very similar, and both of them clearly show the porous feature. The specific surface area of Si(3) is 80 m\textsuperscript{2}/g, quite comparable to the surface area of Si(1) which is 70 m\textsuperscript{2}/g.

**Figure S4.** Morphology comparison (SEM images: a and e, TEM images: the rest) of porous silicon etched using different etchant. a-d: SEM and TEM images of Si(1) (etched in Fe(NO\textsubscript{3})\textsubscript{3}/HF), which show the highly porous structure of the particles, and
individual pores can be discerned from high-magnification TEM images (e.g. D). e-h: SEM and TEM images of Si(3) (etched in Fe(NO$_3$)$_3$/HNO$_3$/HF), which show similar structure to Si(1).

• **Etching on undoped Si**

Silicon nanoparticles bought from Alfa were etched under the same condition as for Si(1). Figure S5 shows that the particles remained solid without any formation of porous structure, which demonstrates that impurities in silicon play a pivotal role in obtaining porous silicon.

![TEM image of undoped silicon nanoparticles after etching, which remained solid structure without formation of pores.](image)

**Figure S5.** TEM image of undoped silicon nanoparticles after etching, which remained solid structure without formation of pores.

• **Tap density of porous silicon electrode**

Tap density is estimated by measuring weight and volume of the active material on the substrate. The electrode has a surface area of 1.5 cm$^2$ and a thickness of 10 µm (Figure S6). The tap density is determined to be about 0.54 g/cm$^3$ for silicon in the electrode.
Figure S6. Side view of electrode showing the thickness of active material layer is around 10 µm

- Nano-indentation on porous silicon particles
A multimode AFM (Veeco Nanoscope IV) was used to carry out the imaging and force-indentation experiment in the tapping mode. The silicon substrate was used as reference to determine the optical sensitivity. The AFM probes used for measurement were silicon probes with spring constant $k=40 \text{ Nm}^{-1}$ and a tip radius of 25 nm. The force indentation was fitted with Hertz model to determine the Young’s modulus$^3$. Figure S7 shows the morphology of Si(1) before and after indentation.

Figure S7. Morphology characterization of a porous silicon particle (Si(1)) before (a) and after (b) indentation using an AFM tip. The protrusion found on the surface after indentation (b) indicates the plastic-like deformation of the porous structure.
3D tomography and structure characterization

For 3D tomography, HAADF-STEM images were taken at TECNAI F20 in the National Center for Electron Microscopy at the Lawrence Berkeley Laboratory. HAADF-STEM images were recorded at single rotation from -75° to 75° at 1° interval. A total of 151 images were aligned using ETOMO to reconstruct the 3D structure of particles. Other STEM and TEM images were recorded at JEOL 2100F at Center for Electron Microscopy and Micro Analysis at the University of Southern California. Figure S8 shows the STEM (reprinted from Figure 1C) of porous Si particles and 3D reconstructions.

![Figure S8](image_url)

**Figure S8.** a. A STEM image of porous silicon particles (reprinted from Figure 1C from main text). b. Reconstructed structure of the particles from HAADF-STEM 3D tomography. c-e. Projected views of orthogonal slices cut through the center of the particle.

Electrode fabrication

Porous silicon particles (Si(1), Si(2)) were first coated with carbon using C$_2$H$_4$ as gas source and Ar as carrier gas under 860 °C for 10 minutes. Graphene oxide (GO) was then mixed with particles in water solution, followed by reduction using hydrazine at 90 °C for 20 minutes. Thermal annealed samples were made by annealing the samples at 700 °C using H$_2$ (5% diluted in Ar) as carrier gas for 20 minutes. The porous silicon
electrodes were fabricated by pasting the slurry (Si : carbon-black : alginic acid sodium salt = 7 : 2 : 1 by weight) on a copper foil and then dried at 90 °C for 6 hours. Later, coin cells were assembled using a lithium foil as the counter/reference electrode; 1 M LiPF$_6$ in dimethyl carbonate / fluoroethylene carbonate (1 : 1 by volume) was used as electrolyte.

- **Elemental mapping of Li and Si**

Figure S9 shows the elemental mapping of Li and Si at lithiated stage for Si(1) (the same sample as the one used in Figure 4d in the main text). EELS spectrum is collected under HAADF-STEM. The red and green colors in Figure S4A are denoted for Si and Li, respectively. Figure S4b-d are the EELS spectra corresponding to the square region shown in Figure S9a. Energy losses in range of 57-70 eV are signals related to Li, while energy losses in range of 99-110 eV are signals related to Si. It is found that in region B and C, Li has much higher EELS signal and Si has almost no signal compared with which is shown in region D, indicating the formation of solid-electrolyte interface (SEI).

**Figure S9.** a. EELS mapping of Li (green) and Si (red) at the enlarged region of Figure 4d (in the main text). b-d. EELS spectra corresponding to the position shown in a. The lithium-rich regions at position A and C indicate the formation of SEI layer.
• **Voltage profile of Si(1) with carbon and GO coating**

![Graph A and B]

**Figure S10.** a. Specific capacity and Coulombic efficiency of the first 5 cycles of Si(1). b. Voltage profile of Si(1) with carbon and GO coating for the 1st, 10th, 100th, and 500th cycle.

• **Etching Si nanoparticles into porous structure**

Silicon nanoparticles were first doped with boron following the method reported previously[^4]. 0.2 g as-prepared boron-doped silicon nanoparticle was immersed in the etchant containing 5 M HF and 1.5 mM Fe(NO$_3$)$_3$ in H$_2$O. Ethanol was added to suppress the foam formation. The reaction was kept under stirring for 30 min, and then washed for characterization. Figure S11 shows the TEM image of porous silicon nanoparticles at different magnifications.

![TEM images]

**Figure S11.** TEM images of porous silicon particles prepared through stain etching on boron-doped silicon nanoparticles.

**References**

3. Sneddon, I. N., The relation between load and penetration in the axisymmetric boussinesq